Vishay High Power Products

Fast Soft Recovery Rectifier Diode, 30 A



ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS		
Maximum forward voltage drop	V_{FM}	30 A, T _J = 25 °C		1.41	V		
Forward slope resistance	r _t	T _{.1} = 150 °C		10.09	mΩ		
Threshold voltage	V _{F(TO)}	1J = 150 C		0.992	V		
Maximum reverse leakage current		T _J = 25 °C	V _B = Rated V _{BBM}	0.1	mA		
Maximum reverse leakage current	IRM	T _J = 150 °C	V _R = nateu V _{RRM}	6	IIIA		

RECOVERY CHARACTERISTICS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	· •		
Reverse recovery time	t _{rr}	I _F at 30 Apk	450	ns	I _{FM} +		
Reverse recovery current	I _{rr}	25 A/μs	6.1	Α	$t_a \mid t_b$		
Reverse recovery charge	Q _{rr}	25 °C	2.16	μC	dir/ Q,,		
Snap factor	S	Typical	0.6		I _{RM(REC)}		

THERMAL - MEC	HANICAL	. SPECIF	ICATIONS		
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range		T _J , T _{Stg}		- 40 to 150	°C
Maximum thermal resistance, junction to case		R_{thJC}	DC operation	0.8	
Maximum thermal resista junction to ambient	nce,	R_{thJA}		40	°C/W
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased	0.2	
Approximate weight				6	g
Approximate weight				0.21	oz.
Mounting torque	minimum			6 (5)	kgf · cm
Mounting torque	maximum			12 (10)	(lbf \cdot in)
			0 TO 04740	30EPF10	
Marking device			Case style TO-247AC modified (JEDEC)	30EPF12	
			Coop and TO 04740	30CPF10	
			Case style TO-247AC	30CPF12	

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For technical questions, contact: diodestech@vishay.com Document Number: 94101 Revision: 09-Dec-09



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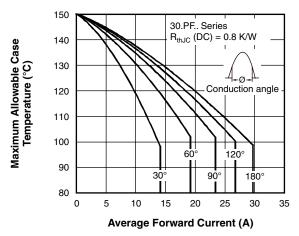


Fig. 1 - Current Rating Characteristics

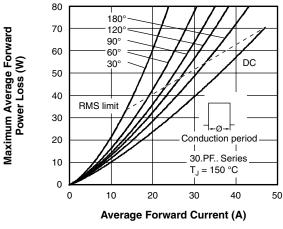


Fig. 4 - Forward Power Loss Characteristics

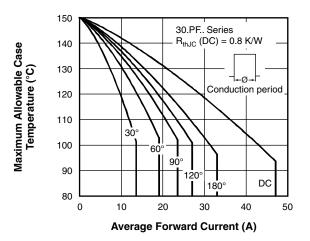


Fig. 2 - Current Rating Characteristics

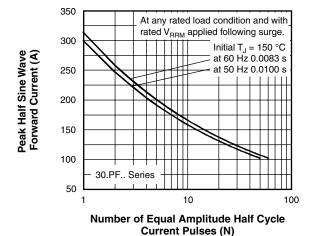


Fig. 5 - Maximum Non-Repetitive Surge Current

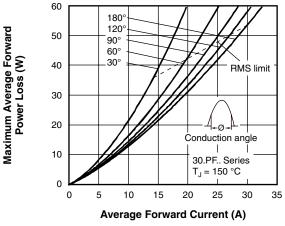


Fig. 3 - Forward Power Loss Characteristics

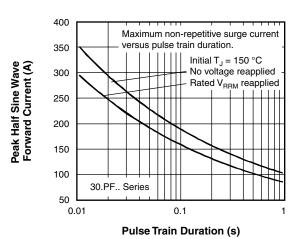


Fig. 6 - Maximum Non-Repetitive Surge Current

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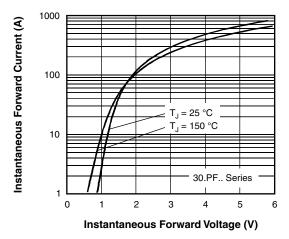


Fig. 7 - Forward Voltage Drop Characteristics

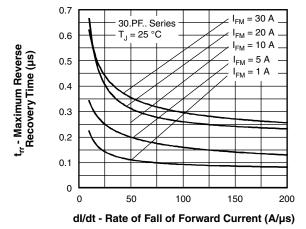


Fig. 8 - Recovery Time Characteristics, $T_J = 25$ °C

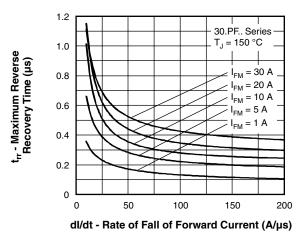


Fig. 9 - Recovery Time Characteristics, $T_J = 150~^{\circ}C$

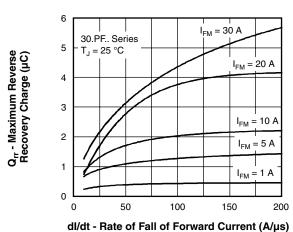
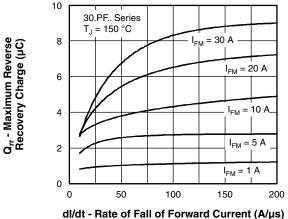


Fig. 10 - Recovery Charge Characteristics, $T_J = 25$ °C



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Fig. 11 - Recovery Charge Characteristics, T_J = 150 °C

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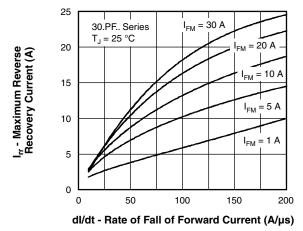


Fig. 12 - Recovery Current Characteristics, T_J = 25 °C

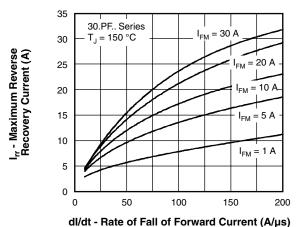


Fig. 13 - Recovery Current Characteristics, T_J = 150 °C

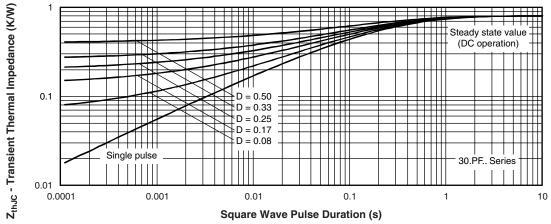


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

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Fast Soft Recovery Rectifier Diode, 30 A



ORDERING INFORMATION TABLE

Device code 30 E P F 12 PbF 1 2 2 3 4 5 6

1 - Current rating (30 = 30 A)

2 - Circuit configuration:

E = Single diode

C = Single diode, 3 pins

Package:

P = TO-247AC modified

4 - Type of silicon:

F = Fast recovery

- Voltage code x 100 = V_{RRM} -

10 = 1000 V 12 = 1200 V

6 - None = Standard production

• PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-247AC modified	www.vishay.com/doc?95253			
Differsions	TO-247AC	www.vishay.com/doc?95223			
Part marking information	TO-247AC modified	www.vishay.com/doc?95255			
Part marking information	TO-247AC	www.vishay.com/doc?95226			
SPICE model		www.vishay.com/doc?95184			

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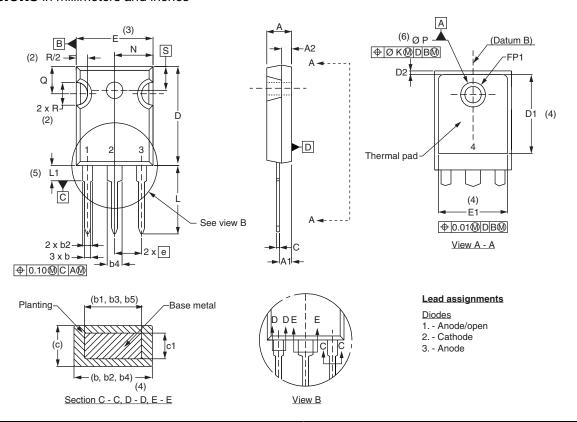
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Vishay Semiconductors

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.37	0.065	0.094	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.86	0.015	0.034	
c1	0.38	0.76	0.015	0.030	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
Е	15.29	15.87	0.602	0.625	3
E1	13.72	=.	0.540	-	
е	5.46	BSC	0.215	BSC	
FK	2.	54	0.0	10	
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
N	7.62	BSC	0.3		
ΦР	3.56	3.66	0.14	0.144	
ФР1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	1.78	0.216	
S	5.51	BSC	0.217	BSC	

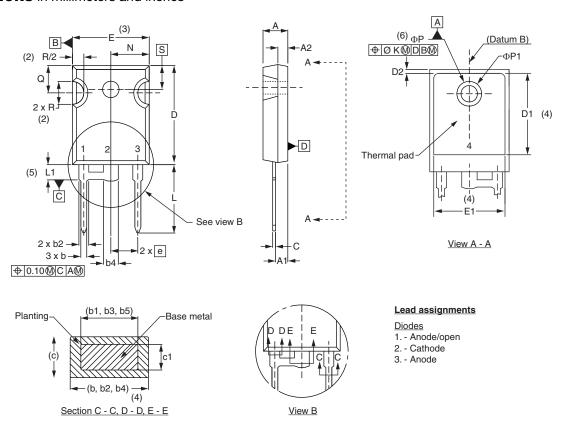
Notes

- $^{(1)}$ Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c



Vishay Semiconductors

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